Flip Chip Substrates BT to ABF Conversion for Two Aerospace & Defense 'XQ' Virtex-II Pro FPGA Devices

XCN10014 (v1.0) April 19, 2010 Product Change Notice

Overview

The purpose of this notification is to announce the conversion of substrate material from BT to ABF build-up for two Aerospace and Defense 'XQ" Virtex®-II Pro FPGA device/packages. There is no change to the form, fit, function or reliability with this change.

Description

For the below affected products, substrate materials will be converted from BT to ABF build–up. The reason for the change is the phase out of UV laser equipment support at the substrate supplier. To ensure continuity of supply for flip chip products, BT will be replaced by ABF since UV laser is not required to form vias with ABF material. The ABF materials set has been qualified and in production for other Virtex-II Pro FPGA, Virtex-4 FPGA and Virtex®-5 FPGA products for 10 years.

Products Affected

This change affects all speed, package, and temperature variations of the commercial (C) and industrial (I) grade devices. Affected part numbers are included in the following table(s):

Table 1: **Product Changes**

Xilinx Product	Package	Change Description
XQ2VP70	FF1704	Build-up materials set change from BT to ABF
XQ2VP70	EF1704	Build-up materials set change from BT to ABF

Note: All SCD parts are also affected.

Key Dates and Ordering Information

Xilinx will begin to ship product using ABF substrate material with date codes on or after 90 days of PCN date.

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Qualification Data

Qualification data & device reliability report for Virtex-II Pro FPGA devices is available in UG116. The extended qualification data related to this PCN is available in RPT141 located in 'Additional Document' section below.

Response

No response is required. For additional information or questions, please contact Xilinx Technical Support.

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Additional Documentation

Qualification Report (RPT141)
https://secure.xilinx.com/webreg/clickthrough.do?cid=140202

Device Reliability Report (UG116):
http://www.xilinx.com/support/documentation/user_guides/ug116.pdf

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
04/19/10	1.0	Initial release.

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